

## ABSTRACT

The present invention provides a nonwoven fabric material prepared from short fibers including thermal-resistant synthetic fibers bound with an inorganic binder, a prepreg and a circuit board using the same. The circuit board has an excellent dimensional stability even at a high temperature, and the circuit board is prevented from warping or being damaged by moisture absorption or the like. The inorganic binder is a residue formed from a low melting point glass solution or a water-dispersible colloidal solution including at least either fibers or particles of low melting point glass dispersed therein. When the binder is used, a chemical covalent bonding by a siloxane bonding is formed.

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